

IN THE CLAIMS

1. (Currently Amended) A glass for a touch panel comprising:

\_\_\_\_\_ a glass substrate having a cut side face, said cut side face at least partially formed by cutting at least with laser light radiation, wherein

\_\_\_\_\_ a surface roughness of ~~the~~ a cut side face of said glass substrate is 50 nm or less, and

\_\_\_\_\_ a depth of a laser mark formed by said laser light radiation on said cut side face is

0.06 nm or more.

2. (Currently Amended) The glass ~~substrate~~ according to claim 1, wherein said glass substrate has a strength of 45 kgf or more and 90 kgf or less based on a static load test.

3. (Currently Amended) The glass ~~substrate~~ according to claim 1, wherein said glass substrate has no crack and pulverized powder at said cut side face.

4. (Currently Amended) The glass ~~substrate~~ according to claim 1, wherein ~~said depths~~ depths of the of laser mark and another laser mark on a second cut side face of said glass substrate marks are different ~~between on a first cut side face of said glass surface and on a second cut side face of said glass substrate~~, said second cut face being different from said first cut side face.

5. (Currently Amended) The glass ~~substrate~~ according to claim 4, wherein ~~said the difference~~ in depths of the laser marks are is different by 2% or more between on said first cut side face and on said second cut side face.

6. (Currently Amended) The glass ~~substrate~~ according to claim 1, wherein said laser mark is formed on a ~~first~~ the cut side face of said glass substrate so as to have a predetermined depth from a first principal surface, and another ~~whereas~~ said laser mark is formed on a second cut side face of said glass substrate so as to have a predetermined depth from a second principal surface, said second cut side face being different from said first cut side face and said second principal surface is ~~the~~ a back surface of said first principal surface.

7. (Original) The glass substrate according to claim 1, wherein a thickness of said glass substrate is 0.25 mm or more and 0.7 mm or less.

8. (Currently Amended) A ~~glass cutting~~ method for cutting a glass plate for a touch panel using laser light radiation and forced cooling, wherein one of a laser power and a scanning speed of said laser light is varied between in a first cutting direction with respect to said glass plate and in a second cutting direction with respect to said glass plate, said second cutting direction being different from said first cutting direction.

9. (Currently Amended) The ~~glass cutting~~ method according to claim 8, wherein one of said laser power and said scanning speed of said laser light is varied by 4% or more between in said first cutting direction and in said second cutting direction.

10. (Currently Amended) A glass cutting method for cutting a glass plate for a touch panel using laser light radiation and forced cooling, comprising the steps of:

radiating said laser light onto a first principal surface of said glass plate so as to cut said glass plate in a first cutting direction; and

radiating said laser light onto a second principal surface of said glass plate so as to cut said glass plate in a second cutting direction, said cutting direction being different from said first cutting direction, and said second principal surface is back surface of said first principal surface.

11. (Original) The glass cutting method according to claim 8, wherein said forced cooling is conducted by spraying any one of a volatile material and a compressed gas.

12. (Original) The glass cutting method according to claim 9, wherein said forced cooling is conducted by spraying any one of a volatile material and a compressed gas.

13. (Currently Amended) A touch panel having a glass substrate, comprising:

the glass substrate having a cut side face, said cut side face being at least partially formed by cutting with laser light radiation;

-a light-transmitting conductive layer formed on a~~the~~ glass substrate; and

a film base material arranged so as to be opposed to said glass substrate with a predetermined distance therebetween, wherein

~~said glass substrate is formed by cutting at least with laser light radiation; and a~~

surface roughness of ~~the~~a cut side face of said glass substrate is 50 nm or less, and a depth of a laser mark formed by said laser light radiation on said cut side face is 0.06 mm or more.

14. (Currently Amended) The touch panel according to claim 13, wherein the depth of the laser mark and another laser mark on a second cut side face of said glass substrate are

~~different, said depths of laser marks are different between on a first cut side face of said glass substrate and on a second cut side face of said glass substrate, said second cut side face being~~

different from said first cut side face.

15. (Original) The touch panel according to claim 13, wherein any one of a peripheral face, a slope and a step is formed on an inner end edge of a window section of a frame on which said glass substrate of said touch panel is fixedly mounted.

16. (Currently Amended) A portable terminal with a touch panel having a glass substrate,  
said touch panel with glass substrate comprising:

the glass substrate having a cut side face, said cut side face being at least partially  
formed by cutting with laser light radiation;

a light-transmitting conductive layer formed on the glass substrate; and

a film base material arranged so as to be opposed to said glass substrate with a  
predetermined distance therebetween, wherein

a surface roughness of the cut side face of said glass substrate is 50 nm or less, and a  
depth of a laser mark formed by said laser light radiation on said cut side face is 0.06 mm or  
more.~~including a touch panel comprising a light-transmitting conductive layer formed on a~~  
~~glass substrate and a film base material arranged so as to be opposed to said glass substrate~~  
~~with a predetermined distance therebetween, wherein said glass substrate is formed by cutting~~  
~~at least with laser light radiation; and a surface roughness of a cut side face of said glass~~  
~~substrate is 50 nm or less, and a depth of a laser mark on said cut side face is 0.06 mm or~~  
~~more.~~

17. (Currently Amended) The portable terminal according to claim 16, wherein the depth of  
the laser mark and another laser mark on a second cut side face of said glass substrate are  
different,~~said depths of laser marks are different between on a first cut side face of said glass~~

Serial No. 10/621,714

Response to Restriction Requirement Dated December 2, 2004

~~substrate and on a second cut side face of said glass substrate,~~ said second cut face being  
different from said first cut side face.